# *In Situ* synthesis of TiN-reinforced Si<sub>3</sub>N<sub>4</sub> matrix composites using Si and sponge Ti powders

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Dense Si<sub>3</sub>N<sub>4</sub>-TiN composites from Si and sponge Ti (0–40 wt %) powders were produced by *in situ* reaction-bonding and post-sintering under N<sub>2</sub> atomosphere. The fracture strength and toughness of Si<sub>3</sub>N<sub>4</sub>-17% TiN composite were found to be 537.9 MPa and 10.4 MPa m<sup>1/2</sup>, respectively. In the reaction-bonded bodies, Si<sub>3</sub>N<sub>4</sub> grains were constructed with  $\alpha$ - and  $\beta$ -Si<sub>3</sub>N<sub>4</sub> structure as well as TiN and some amounts of residual Si phase. After post-sintering, the residual Si and  $\alpha$ -Si<sub>3</sub>N<sub>4</sub> grains were transformed to  $\beta$ -Si<sub>3</sub>N<sub>4</sub> grains with rod-like shape. No intermetallic compounds (e.g., TiSi<sub>2</sub>, Ti<sub>5</sub>Si<sub>3</sub> and Ti<sub>5</sub>Si<sub>4</sub>) were formed at the interfaces between Si<sub>3</sub>N<sub>4</sub> and TiN grains. The main toughening mechanisms were crack deflection and crack bridging caused by rod-like Si<sub>3</sub>N<sub>4</sub> grains which were randomly dispersed in sintered body. Microcracking due to the dispersion of *in situ* formed TiN particles also contributed to the toughening of the sintered body. © *1999 Kluwer Academic Publishers* 

## 1. Introduction

Although  $Si_3N_4$  ceramic has excellent mechanical properties such as fracture toughness and strength compared with other ceramics, it is not so widely used as industrial material except for the cutting tools and some engine components. The main reason is the high cost and low fracture toughness of  $Si_3N_4$  sintered body compared with metallic systems.

Reaction-bonded silicon nitride (RBSN) which has some advantages such as low price of raw powders, easy control of dimensions and low cost of production, has been actively developed since early 1970's. However, the existence of residual Si phases and high porosity of the RBSN bodies limit the application of RBSN materials. Recently, RBSN has been re-illuminated since the removal of residual Si and pores has been made possible by post-sintering process. Furthermore, the shape of Si<sub>3</sub>N<sub>4</sub> grains in the Si<sub>3</sub>N<sub>4</sub> sintered body can be easily controlled by the high temperature process. In order to improve the mechanical properties of monolithic Si<sub>3</sub>N<sub>4</sub> ceramic, various types of SiC [1-3], ZrO<sub>2</sub> [4-6] and TiN [7–12] powders were used as toughening agents. Among these, TiN particles have been found to be particularly useful due to the microcracking mechanism when optimum amounts of TiN particles are dispersed in Si<sub>3</sub>N<sub>4</sub> matrix. Up to now, there are three processing routes of making Si<sub>3</sub>N<sub>4</sub>-TiN composites. The first method is a conventional liquid phase sintering using mixtures of Si<sub>3</sub>N<sub>4</sub>, TiN and some amounts of sintering additives [7, 8]. The second one is a CVD method using a gaseous mixture of  $SiC_{14}$ -Ti $C_{14}$ -NH<sub>3</sub>-H<sub>2</sub> [9]. In this case, the nanometer-sized TiN crystallines dispersed in the Si<sub>3</sub>N<sub>4</sub> matrix grains interact with cracks, generating crack bridging and microcracking [10]. The third process is a reaction-bonding technique using a mixture of Si, TiN and some contents of sintering additives [11, 12] In this work, the synthesis of Si<sub>3</sub>N<sub>4</sub>-TiN composite from Si and sponge Ti powders was carried out by the in situ reaction-bonding followed by gas pressure sintering technique. The purpose of the present work is to investigate the crystal structure of Si<sub>3</sub>N<sub>4</sub>, the relationships between microstructure and material properties of the in situ reaction-bonded-bodies which depend on the sintering conditions, Ti contents, and the gas-pressure. The sintered Si<sub>3</sub>N<sub>4</sub>-TiN composites were examined by optical microscope (OM), X-ray diffractometer (XRD), transmission electron electron microscopy (TEM) and scanning electron microscopy (SEM).

## 2. Experimental

Fig. 1 shows SEM micrographs of Si with irregular shapes (a) and Ti powders with sponge type (b) used in present work. The average size of Si powders used was  $10 \,\mu$ m, but large-sized particles (about  $20 \,\mu$ m) were also observed. The average size of Ti powder particles was about  $100 \,\mu$ m. Some Ti powders agglomerated with fine particles were also observed as indicated with arrow heads. The Si, sponge Ti powders (0–40 wt %) and sintering additives (5 wt % Y<sub>2</sub>O<sub>3</sub> and



Figure 1 SEM micrographs of Si (a) and sponge Ti (b) powders.

2 wt % Al<sub>2</sub>O<sub>3</sub>) were throughly mixed in ethanol using a planetary ball mill and Si<sub>3</sub>N<sub>4</sub> balls as milling media. The mixtures were dried on a hot plate while stirring. The powder mixture was pressed into pellets and CIPed at 250 MPa. The pellets, 40 mm in diameter were nitrided in flowing N<sub>2</sub>-10% H<sub>2</sub> gas mixture at 1350 °C for 10, 20 and 30 h. To improve the mechanical properties of a nitrided momolithic Si<sub>3</sub>N<sub>4</sub> and a Si<sub>3</sub>N<sub>4</sub>-17% TiN composite made at 1350 °C for 20 h, the post-sintering was carried out at 2000 °C for 3.5 h under 66 MPa N<sub>2</sub> gas pressure. The residual Si, TiN phases and porosity were identified by OM. The XRD and SEM (JSM-5300) were used to examine crystal structure and morphology of fracture surfaces of the Si<sub>3</sub>N<sub>4</sub>-TiN composite over a wide scale. Using TEM (JEM-2000EX), the detailed crystal structures, internal microstructure and interfacial structure between Si<sub>3</sub>N<sub>4</sub> and TiN phases were examined. TEM observation was performed with a 200 kV electron microscope. The average Vickers hardness was measured by indenting with a load of 9.8N (30 points/a sample), while the average bending strength was measured by 3-point bending method at a crosshead speed of 0.5 mm/min using each 6 specimens with  $3 \times$  $4 \times 30$  mm bars. The fracture toughness K<sub>IC</sub> was calculated by indentation method with a load of 294N [13].

#### 3. Results and discussion

#### 3.1. Microstructure and material properties of reaction-sintered Si<sub>3</sub>N<sub>4</sub>-TiN composites

Fig. 2 is optical micrographs showing the polished surfaces of samples of Si<sub>3</sub>N<sub>4</sub>-TiN composites reactionbonded at 1350 °C for 20 h. In these images, the regions of black and white contrasts correspond to residual pores and Si phase, respectively. As can be seen in this images, a relatively small amount of residual Si particles were observed in Si<sub>3</sub>N<sub>4</sub>-17% TiN composite. The residual Si phase was remarkably higher in samples with higher Ti contents. Many residual Si particles about 7  $\mu$ m size were observed with white contrasts in the Si<sub>3</sub>N<sub>4</sub>-35% TiN composite. The relatively poor



*Figure 2* Optical micrographs showing the TiN phase in the reaction-bonded  $Si_3N_4$ -TiN composites at 1350 °C for 20 h. (a):  $Si_3N_4$ -0%TiN, (b):  $Si_3N_4$ -17%TiN, (c):  $Si_3N_4$ -26%TiN, (d):  $Si_3N_4$ -35%TiN.

nitridation of matrix in the Si<sub>3</sub>N<sub>4</sub>-35% TiN composite can probably be attributed to the followings; N<sub>2</sub> gas preferably reacts with Ti particles than Si powder. The other reason may be due to the excessive overheating during the nitridation as a result of the exothermic nature of the process. Melting of Si powders may lead to a blockage of pore channels, thus making it difficult for N<sub>2</sub> gas to penetrate the compact. Although in the black and white image, the residual Si and TiN phases do not clearly distinguish, when we observed the OM, the



Figure 3 Ti contents dependency of relative density, Vickers hardness and bending strength in reaction-bonded  $Si_3N_4$ -TiN composites at 1350 °C for 20 h.

residual Si and TiN particles were seen with white and yellow contrasts, respectively. The OM observation of the reaction-bonded bodies confirmed that many raw Ti powders with about 100  $\mu$ m were broken down to about 25  $\mu$ m and well dispersed in Si<sub>3</sub>N<sub>4</sub> matrix. As can be seen in Fig. 2b,c and d, most of the TiN particles contained a few of large pores, and many large crevices caused by the falling off of Si<sub>3</sub>N<sub>4</sub> grains during the polishing.

Fig. 3 shows relative density, Vickers hardness and bending strength of  $Si_3N_4$ -TiN composites after reaction-bonding as a function of TiN contents. As can be seen in this graph, the values of relative density and hardness showed a maximum of about 68% and 520 Hv respectively in the  $Si_3N_4$ -17% TiN composite. However, in the comparison with other available data on reaction-bonded  $Si_3N_4$ , these values are very low [11]. A general decline in properties was observed in samples containing more than 17% TiN. This behavior was due to low density and the existence of large amount of residual Si phase. The existence of microcracks of residual Si particles in the reaction-bonded body also contributed to the deterioration of the material properties [14].

Fig. 4 shows the SEM fracture surfaces made by 3-point bending test. As can be seen in the monolithic  $Si_3N_4$  body (a), the fracture surface looked more flater than that of TiN-dispersed  $Si_3N_4$  sintered body (c and e). In the enlarged image (b), residual pores and Si



*Figure 4* SEM images showing fracture morphology of reaction-bonded  $Si_3N_4$ -TiN composites at 1350 °C for 20 h. (a):  $Si_3N_4$ -0% TiN, (c):  $Si_3N_4$ -17% TiN, (e):  $Si_3N_4$ -26% TiN. (b), (d) and (f): Enlarged micrographs of (a), (c) and (e), respectively.

particles which appeared with cleavage fracture are also observed. In the 17% TiN composite (c and d), only a few residual Si particles were observed as seen in Fig. 2. Pull-out behavior of TiN particles appeared in the TiNdispersed Si<sub>3</sub>N<sub>4</sub> composites, so that TiN particles and traces of TiN particles as indicated with arrowheads (c and e) are frequently observed on the fracture surfaces. Most of the pulled-out TiN particles were very large in size about 100  $\mu$ m, however some transgranular fractures also occurred in small sized-TiN particles. A few of residual cracks in the TiN particles were observed as indicated with an arrow.

Fig. 5 shows optical micrographs of reaction-bonded  $Si_3N_4$ -17% TiN composite as a function of reaction time at 1350 °C. In the sample nitrided for 10 h, many fine residual Si phase with white contrast were observed around coarse TiN particles, but the residual Si phase showed a tendency to diminish with increasing reaction times. Also, many pores were observed as indicated

with arrowheads. On the other hand, the TiN particles with large size seem to become dense particles as reaction time gradually increases. The regions with gray colour inside the coarse TiN particles corresponded to  $Si_3N_4$  phase in which Si particles were possibly introduced into the sponge Ti particles during the ball milling process. In order to investigate whether the intermetallic compounds such as  $TiSi_2$ ,  $Ti_5Si_3$  and  $Ti_5Si_4$  were formed during the reaction sintering or not, we carried out the X-ray diffraction as a dependency of reaction time.

Fig. 6c,d and e are XRD profiles of the reactionbonded  $Si_3N_4$ -20% TiN composite at 1350 °C for 10, 20, 30 h, respectively. For a comparison, XRD profiles of raw Si (a) and sponge Ti (b) are also inserted. As can be seen in diagram, the intensity of residual Si crystals gradually decreased with increasing reaction times, however some residual Si peaks were observed after reaction-bonding for 30 h. Observations of the



Figure 5 Optical micrographs showing TiN phase in reaction-bonded Si<sub>3</sub>N<sub>4</sub>-17% TiN composite at 1350 °C. (a): For 10 h, (b): For 20 h, (c): For 30 h.



Figure 6 X-ray diffraction patterns of reaction-sintered Si<sub>3</sub>N<sub>4</sub>-17% TiN composites at 1350 °C. (a): Raw Si powders, (b): Raw Ti powders, (c): For 10 h, (d): For 20 h, (e): For 30 h.

crystal structure of reaction-bonded Si<sub>3</sub>N<sub>4</sub> phase indicated that irrespective of the duration of the reaction  $\alpha$ - and  $\beta$ -types always coexisted in the sample. From our recent TEM work on the reaction-bonded Si<sub>3</sub>N<sub>4</sub> body [14], it is confirmed that  $\alpha$ -Si<sub>3</sub>N<sub>4</sub> phases are directly formed by nitridation of Si particles. In this case, cracks and dislocations in the Si particles play an important role to explain the nitridation mechanism of large sized Si particles. Generally, when the Si particles are nitrided to Si<sub>3</sub>N<sub>4</sub> phase, it is well known that the Si coated with an amorphous oxide film are first decomposed, and then, Si<sub>3</sub>N<sub>4</sub> nuclei are formed on the surfaces of Si particles [15]. As the nuclei gradually grow with submicron-sized  $\alpha$ -Si<sub>3</sub>N<sub>4</sub> grains, dislocations den-



*Figure 7* Optical micrographs GPSed monolithic  $Si_3N_4$  (a) and  $Si_3N_4$ -17% TiN composite (b) at 2000 °C for 3.5 h. A few of residual Si phase are observed in the dark circled regions. Arrowheads indicate fine sized TiN particles.

sity in the Si particles increases and continuously piled up [14]. Microcracks are generated at the pile-up regions of dislocation by the lattice mismatch between  $\alpha$ -Si<sub>3</sub>N<sub>4</sub> and Si, and these microcracks gradually penetrate into all regions of Si particles with increasing sintering time [14]. This facilitates the supply of  $N_2$  gas into interior part of Si crystals, leading to the acceleration of the nitridation process. In addition, needle-like  $\beta$ -Si<sub>3</sub>N<sub>4</sub> crystals were also observed around comparatively large-sized pores [14]. This indirectly means that  $\beta$ -Si<sub>3</sub>N<sub>4</sub> grains can easily be formed without the existence of a compressive effect. On the other hand, the intermetallic compounds (e.g., TiSi<sub>2</sub>, Ti<sub>5</sub>Si<sub>3</sub> and Ti<sub>5</sub>Si<sub>4</sub>) which were expected for plastic deformation toughening were not detected. The residual Ti peaks were not observed in the reaction-sintered body even after 10 h (c), and this result indicates that sponge Ti particles are easily nitrided than Si particles.

# 3.2. Microstructure and material properties of post-sintered monolithic $Si_3N_4$ and $Si_3N_4$ -17%TiN composite at 2000 °C for 3.5 h

Fig. 7 shows the polished optical micrographs of GPSed monolithic  $Si_3N_4$  and  $Si_3N_4$ -17% TiN composite. In the monolithic Si<sub>3</sub>N<sub>4</sub> body, a few of residual Si particles with less than  $0.5 \,\mu m$  were observed with white contrast at the interior region of sintered body as indicated with dark circles, but no such observation was made on the out-side regions. In the Si<sub>3</sub>N<sub>4</sub>-17% TiN composite, the residual Si particles were not observed even on the interior regions. The TiN particles homogeneously dispersed in the Si<sub>3</sub>N<sub>4</sub> matrix existed with two types. One type is the large sized particles which contained a few residual pores and Si<sub>3</sub>N<sub>4</sub> phase, the other is the spherical shape with less than 0.7  $\mu$ m in size as indicated with arrowheads. The latter is formed by the breakdown of the fine sponge-type Ti particles which was seen in Fig. 1b. A few residual Si in Fig. 7a and spherical TiN particles in Fig. 7b were distinguished by colour, that is, they were seen with white and yellow contrasts, respectively.

Fig. 8 shows XRD profiles of GPSed monolithic  $Si_3N_4$  (a) and  $Si_3N_4$ -17% TiN composite (b). Most of



*Figure 8* X-ray diffraction patterns of Si<sub>3</sub>N<sub>4</sub>-TiN body. (a): Reaction-sintered at 1350 °C for 20 h, (b): Reaction-sintered and GPSed at 2000 °C for 3.5 h.



*Figure 9* (a) Typical TEM image of GPSed  $Si_3N_4$ -17% TiN composite. Arrowheads indicate the existence of amorphous phase at the triple regions. (b) TEM image showing the fine sized TiN particle. Arrowheads indicate many dislocation contrasts.

residual Si phases which existed in reaction-bonded bodies (in Fig. 6) were nitrided during the GPS process, leading to elimination of Si peaks in the XRD pattern. Only  $\beta$ -type Si<sub>3</sub>N<sub>4</sub> and NaCl type TiN peaks were detected in the XRD patterns. These results indicate that the GPS process facilitate the nitridation of residual Si phase. In addition,  $\alpha$ -Si<sub>3</sub>N<sub>4</sub> crystals were fully transformed to  $\beta$ -Si<sub>3</sub>N<sub>4</sub> crystals during the high temperature post-sintering process.

Fig. 9 shows TEM images of GPSed Si<sub>3</sub>N<sub>4</sub>-17% TiN composite, and the corresponding electron diffraction patterns taken from the dark circles. As can be seen in Fig. 9a, the rod-like shaped grains about  $1.5 \,\mu\text{m}$  in diameter were observed, and some fine sized Si<sub>3</sub>N<sub>4</sub> crystals of about  $0.5 \,\mu m$  diameter were also observed between them. The inserted electron diffraction pattern taken from a fine sized Si<sub>3</sub>N<sub>4</sub> grain shows [001] zone axis of  $\beta$ -Si<sub>3</sub>N<sub>4</sub>. As frequently observed in hot-pressed Si<sub>3</sub>N<sub>4</sub> body [2], the amorphous regions as marked with arrowheads were located at the triple points and grain boundaries. Fig. 8b is an enlarged TEM image showing a spherical TiN particle embedded in a Si<sub>3</sub>N<sub>4</sub> grain, and an electron diffraction pattern shows [110] zone axis of TiN phase. As can be seen in this image, a few dislocations originating from TiN particles were observed in Si<sub>3</sub>N<sub>4</sub> grains. From the observations made of the large dislocation lines, it is quite clear that they were formed during the cooling process after sintering, which caused a mismatching of thermal expansion coefficients and lattice parameters between Si<sub>3</sub>N<sub>4</sub> and TiN particles. Generally, Si<sub>3</sub>N<sub>4</sub> ceramic does not easily deform at room temperature. From our recent works on the fracture characteristic of Si<sub>3</sub>N<sub>4</sub> matrix composites [2, 3, 6, 10], it was confirmed that when a crack made by indentation propagates into Si<sub>3</sub>N<sub>4</sub> sintered body, some partial dislocations occur near crack process and tip zones. Observation of interfaces between Si<sub>3</sub>N<sub>4</sub> and TiN particles as marked with white arrows in Fig. 9b indicated that no intermetallic compounds are formed for the reaction process. Interfaces of Si<sub>3</sub>N<sub>4</sub>-TiN composites synthesized by CVD process, also showed the incoherent interfacial structure without any reaction phases [10]. However, it is well known that Si<sub>3</sub>N<sub>4</sub> ceramic is very reactive with Al alloys [16, 17]. For an example, in the  $Si_3N_4$  whisker-

TABLE I Material properties of GPSed monolithic  $Si_3N_4$  and  $Si_3N_4$ -TiN composites (at 2000 °C for 3.5 h)

Specimen	Relative density (%)	Hardness (kg/m <sup>2</sup> )	$\frac{K_{IC}}{(MPa \cdot m^{1/2})}$	Fracture strength (MPa)
Si <sub>3</sub> N <sub>4</sub> -0%TiN	98.5	1486.3	7.9	495.1
Si <sub>3</sub> N <sub>4</sub> -17%TiN	94.8	1462.5	10.4	537.9

reinforced 7074Al matrix composite, many  $\beta$ -Mg<sub>2</sub>SiO<sub>4</sub> reaction compounds about 40 nm were formed at the interfaces between 7064Al and Si<sub>3</sub>N<sub>4</sub> whisker [17]. The existence of nitrogen atmosphere during the reaction bonding process probably explains why no intermetallic compounds were formed. Our TEM observations confirmed that large TiN particles were the result of an agglomeration of polycrystals of TiN particles containing some residual pores and Si<sub>3</sub>N<sub>4</sub> phases. Microcracks were not observed around TiN particles.

Table I shows the material properties of GPSed monolithic  $Si_3N_4$  and  $Si_3N_4$ -17% TiN composite. The relative densities of monolithic  $Si_3N_4$  and  $Si_3N_4$ -17% TiN composite are 98.5 and 94.8%, respectively. Inspite of low relative density and existence of large sized TiN particles in the  $Si_3N_4$ -17% TiN composite, the values of hardness and fracture strength are 1462.5 kg/mm<sup>2</sup> and 537.9 MPa. In particular, the average fracture toughness measured by indentation method also shows very high value of 10.4 MPam<sup>1/2</sup>.

Fig. 10 shows SEM fracture surfaces of GPSed monolithic  $Si_3N_4$  (a) and  $Si_3N_4$ -17% TiN composite (b and c) made by 3-point bending test. As can be seen in both sintered bodies, the rough surfaces were observed in the fracture surfaces. This observation indicates that main fracture of both GPSed bodies was the intergranular type. On the fracture surface, there was evidence of pull-out of many rod-like  $\beta$ -Si<sub>3</sub>N<sub>4</sub> grains with high aspect ratio and their traces. This is similar to an observation previously made in SiC-whisker-reinforced Si<sub>3</sub>N<sub>4</sub> composite [2]. This observation indicates that the microstructural control of matrix is enhanced by the post-sintering process. The appearance of typical intergranular fracture and pull-out phenomenon of rod-like Si<sub>3</sub>N<sub>4</sub> grains on the fracture surfaces indicate crack



Figure 10 SEM fracture surfaces showing intergranular fracture of GPSed monolithic Si<sub>3</sub>N<sub>4</sub> (a) and Si<sub>3</sub>N<sub>4</sub>-17% TiN composite (b and c).



Figure 11 Optical micrographs showing crack propagation of post-sintered monolithic Si<sub>3</sub>N<sub>4</sub> (a) and Si<sub>3</sub>N<sub>4</sub>-17% TiN composite.

deflection and crack bridging mechanisms required to improve the fracture toughness. Furthermore, in the Si<sub>3</sub>N<sub>4</sub>-17% TiN composite (in Fig. 10b), the diameter of rod-like Si<sub>3</sub>N<sub>4</sub> grains was larger than that of monolithic Si<sub>3</sub>N<sub>4</sub> grains (in Fig. 10b). Mitomo and Tajima reported that the relationship between fracture toughness and diameter of rod-like Si<sub>3</sub>N<sub>4</sub> grains is such that that the toughening effects are increased with increasing average diameter of rod-like Si<sub>3</sub>N<sub>4</sub> grains [18]. The dispersion of TiN particles enhances fracture toughness by microcracking due to the existence of strain fields around the TiN particles [19] as shown in Fig. 9b. In the Fig. 10c, a large-sized TiN particle with about  $60 \,\mu m$ as indicated with a dot-lined region is intergranularly fractured, so that the sharped grains are observed. The existence of residual pores and Si<sub>3</sub>N<sub>4</sub> phase in the largesized TiN particles leads to the intergranular fracture of TiN particles.

Fig. 11 is optical micrographs showing crack propagation of GPSed monolithic  $Si_3N_4$  and  $Si_3N_4$ -TiN composite made by Vickers indentation with a load of 294N. In Fig. 11a, a crack propagated from the diamond cone, is well observed showing some crack deflection. On the other hand, in the  $Si_3N_4$ -17% TiN composite, the main crack is very short length compared with that of monolithic  $Si_3N_4$ . In addition, microcracks are observed in the TiN particle as indicated with arrowheads. It is supposed that when a crack propagated into TiN particles, the crack propagation energy is diminished by the formation of many microcracks at the interior of TiN particles. From the above results, it is concluded that high fracture toughness in the  $Si_3N_4$ -17% TiN composite originates from the multi toughening mechanisms of crack bridging, crack deflection and microcracking.

#### 4. Conclusions

From the present study of *in situ* synthesis of Si<sub>3</sub>N<sub>4</sub>-TiN composite using Si and sponge Ti powders, the following results were obtained.

(1) In the reaction bonded composites, the values of hardness and relative densities are maximum in the  $Si_3N_4$ -17% TiN composite.

(2) The dispersed Ti particles were fully nitrided to TiN phase at  $1350 \,^{\circ}$ C, but intermetallic compounds (e.g., TiSi<sub>2</sub>, Ti<sub>5</sub>Si<sub>3</sub> and Ti<sub>5</sub>Si<sub>4</sub>) were not formed at the interface between Si<sub>3</sub>N<sub>4</sub> and TiN grains.

(3) After the post-sintering, the equiaxed  $\alpha$ -Si<sub>3</sub>N<sub>4</sub> grains that existed in the reaction-bonded bodies were transformed to rod-like  $\beta$ -Si<sub>3</sub>N<sub>4</sub>. The fracture strength of Si<sub>3</sub>N<sub>4</sub>-17%TiN composite was comparatively low, 537.9 MPa, but the fracture toughness was 10.4 MPa m<sup>1/2</sup>.

(4) The fracture mode of GPSed  $Si_3N_4$ -17% TiN composite was typically intergranular, whilst the main

toughening effect was due to crack deflection and crack bridging caused by well developed rod-like  $Si_3N_4$  grains. Microcracking caused by the difference in thermal expansion coefficient and lattice parameter between  $Si_3N_4$  and TiN phases also contributed to the toughening of the composite.

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